

IN THE CLAIMS

Claim 1 (original): A method of making an IC package mold lock comprising the steps of:

- providing a first niche in a leadframe surface;
- providing an opposing niche in an opposing leadframe surface, the opposing niche partially intersecting with the first niche such that an aperture in the leadframe is defined by the intersecting portions, and such that a key is defined by the nonintersecting portions; and
- encapsulating the key with mold compound to form a mold lock.

Claim 2 (original): The method of claim 1 wherein the encapsulating step further comprises filling the first niche, opposing niche, and aperture with mold compound.

Claim 3 (original): The method of claim 1 wherein the providing steps further comprise the steps of masking and etching the leadframe surfaces.

Claim 4 (original): The method of claim 1 wherein the step of providing an opposing niche further comprises the step of providing an opposing niche axially unaligned with a first niche of approximately identical same size and shape.

Claim 5 (original): The method of claim 1 wherein the step of providing an opposing niche further comprises the step of providing an opposing niche axially aligned with a first niche of nonidentical size and shape.

Claim 6 (original): The method of claim 1 wherein the leadframe surfaces further comprise lead finger surfaces.

Claim 7 (original): The method of claim 1 wherein the leadframe surfaces further comprise die pad surfaces.